



2.5-V/3.3-V OSCILLATOR GAIN STAGE/BUFFERS

FEATURES

- Low-Voltage PECL Input and Low-Voltage PECL or LVDS Outputs
- Clock Rates to 2 GHz
 - 140-ps Output Transition Times
 - 0.11 ps Typical Intrinsic Phase Jitter
 - Less than 630 ps Propagation Delay Times
- 2.5-V or 3.3-V Supply Operation

- 2-mm × 2-mm Small-Outline No-Lead Package

APPLICATIONS

- PECL-to-LVDS Translation
- Clock Signal Amplification

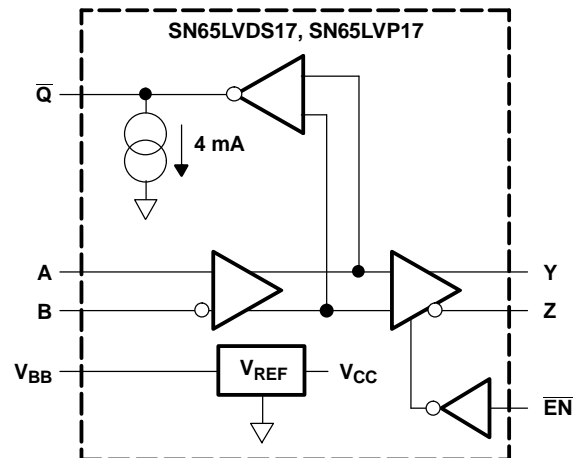
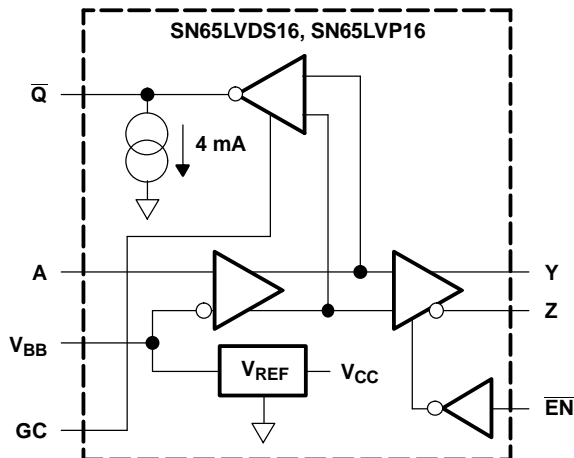
DESCRIPTION

These four devices are high-frequency oscillator gain stages supporting both LVPECL or LVDS on the high gain outputs in 3.3-V or 2.5-V systems. Additionally, provides the option of both single-ended input (PECL levels on the SN65LVx16) and fully differential inputs on the SN65LVx17.

The SN65LVx16 provides the user a Gain Control (GC) for controlling the \bar{Q} output from 300 mV to 860 mV either by leaving it open (NC), grounded, or tied to V_{CC} . (When left open, the \bar{Q} output defaults to 575 mV.) The \bar{Q} on the SN65LVx17 defaults to 575 mV as well.

Both devices provide a voltage reference (V_{BB}) of typically 1.35 V below V_{CC} for use in receiving single-ended PECL input signals. When not used, V_{BB} should be unconnected or open.

All devices are characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AVAILABLE OPTIONS⁽¹⁾

| INPUT | OUTPUT | GAIN CONTROL | BASE PART NUMBER | PART MARKING |
|--------------|--------|--------------|------------------|--------------|
| Single-ended | LVDS | Yes | SN65LVDS16 | EL |
| Single-ended | LVPECL | Yes | SN65LVP16 | EK |
| Differential | LVDS | No | SN65LVDS17 | EN |
| Differential | LVPECL | No | SN65LVP17 | EM |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

| | UNIT |
|---|-------------------------------------|
| V _{CC} Supply voltage ⁽²⁾ | −0.5 V to 4 V |
| V _I Input voltage | −0.5 V to V _{CC} + 0.5 V |
| V _O Output voltage | −0.5 V to V _{CC} + 0.5 V |
| I _O V _{BB} output current | ±0.5 mA |
| HBM electrostatic discharge ⁽³⁾ | ±3 kV |
| CDM electrostatic discharge ⁽⁴⁾ | ±1500 V |
| Continuous power dissipation | See Power Dissipation Ratings Table |

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, except differential voltages, are with respect to network ground see [Figure 1](#).

(3) Tested in accordance with JEDEC Standard 22, Test Method A114-A-7

(4) Tested in accordance with JEDEC Standard 22, Test Method C101

DISSIPATION RATINGS

| PACKAGE | CIRCUIT BOARD MODEL | T _A ≤ 25°C POWER RATING | DERATING FACTOR ABOVE T _A = 25°C ⁽¹⁾ | T _A = 85°C POWER RATING |
|---------|-----------------------|---------------------------------------|---|---------------------------------------|
| DRF | Low-K ⁽²⁾ | 403 mW | 4.0 mW/°C | 161 mW |
| | High-K ⁽³⁾ | 834 mW | 8.3 mW/°C | 333 mW |

(1) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

(2) In accordance with the Low-K thermal metric definitions of EIA/JESD51-3.

(3) In accordance with the High-K thermal metric definitions of EIA/JESD51-7.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | VALUE | UNIT | |
|--|-----------------|---|------|----|
| θ _{JB} Junction-to-board thermal resistance | | 93.3 | °C/W | |
| θ _{JC} Junction-to-case thermal resistance | | 101.7 | | |
| P _D Device power dissipation | Typical | V _{CC} = 3.3 V, T _A = 25°C, 2 GHz, LVDS | 132 | |
| | | V _{CC} = 3.3 V, T _A = 25°C, 2 GHz, LVPECL | 83 | |
| | Maximum | V _{CC} = 3.6 V, T _A = 85°C, 2 GHz, LVDS | 173 | mW |
| | | V _{CC} = 3.6 V, T _A = 85°C, 2 GHz, LVPECL | 108 | |

RECOMMENDED OPERATING CONDITIONS

| | | | MIN | NOM | MAX | UNIT |
|------------|--|-------------------------|---------------------|------------|-----------------------|--------------|
| V_{CC} | Supply voltage | | 2.375 | 2.5 or 3.3 | 3.6 | V |
| V_{IC} | Common-mode input voltage ($V_{IA} + V_{IB}$)/2 | SN65LVDS17 or SN65LVP17 | 1.2 | | $V_{CC} - (V_{ID}/2)$ | V |
| $ V_{ID} $ | Differential input voltage magnitude $ V_{IA} - V_{IB} $ | SN65LVDS17 or SN65LVP17 | 0.08 | | 1 | V |
| V_{IH} | High-level input voltage to \overline{EN} | \overline{EN} | | 2 | V_{CC} | V |
| | | SN65LVDS16 or SN65LVP16 | $V_{CC} - 1.17$ | | $V_{CC} - 0.44$ | |
| V_{IL} | Low-level input voltage to \overline{EN} | \overline{EN} | | 0 | 0.8 | V |
| | | SN65LVDS16 or SN65LVP16 | $V_{CC} - 2.25$ | | $V_{CC} - 1.52$ | |
| I_O | Output current to V_{BB} | | -400 ⁽¹⁾ | | 400 | μ A |
| R_L | Differential load resistance, | | 90 | | 132 | Ω |
| T_A | Operating free-air temperature | | -40 | | 85 | $^{\circ}$ C |

(1) The algebraic convention, where the least positive (more negative) value is designated minimum, is used in this data sheet.

ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT | |
|---|---|---|--------------------|-----------------|-----------------|---------|
| I_{CC} | Supply current | | 40 | 48 | mA | |
| | $R_L = 100 \Omega$, \overline{EN} at 0 V, Other inputs open | | | | | |
| | Outputs unloaded, \overline{EN} at 0 V, Other inputs open | | 25 | 30 | | |
| V_{BB} | Reference voltage ⁽²⁾ | $I_{BB} = -400 \mu$ A | $V_{CC} - 1.44$ | $V_{CC} - 1.35$ | $V_{CC} - 1.25$ | V |
| I_{IH} | High-level input current, \overline{EN} | $V_I = 2$ V | -20 | | 20 | μ A |
| I_{IAH} or I_{IBH} | High-level input current, A or B | $V_I = V_{CC}$ | -20 | | 20 | |
| I_{IL} | Low-level input current, \overline{EN} | $V_I = 0.8$ V | -20 | | 20 | |
| I_{IAL} or I_{IBL} | Low-level input current, A or B | $V_I = GND$ | -20 | | 20 | |
| SN65LVDS16/17 Y AND Z OUTPUT CHARACTERISTICS | | | | | | |
| $ V_{OD} $ | Differential output voltage magnitude, $ V_{OY} - V_{OZ} $ | See Figure 1 and Figure 2 | 247 | 340 | 454 | mV |
| $\Delta V_{OD} $ | Change in differential output voltage magnitude between logic states | | | | 50 | |
| $V_{OC(SS)}$ | Steady-state common-mode output voltage (see Figure 3) | | | 1.125 | | 1.375 |
| $\Delta V_{OC(SS)}$ | Change in steady-state common-mode output voltage between logic states | See Figure 3 | -50 | | 50 | mV |
| $V_{OC(PP)}$ | Peak-to-peak common-mode output voltage | | | 50 | | |
| I_{OYZ} or I_{OZZ} | High-impedance output current | \overline{EN} at V_{CC} , $V_O = 0$ V or V_{CC} | -1 | | 1 | μ A |
| I_{OYS} or I_{OZS} | Short-circuit output current | \overline{EN} at 0 V, V_{OY} or $V_{OZ} = 0$ V | -62 | | 62 | mA |
| $I_{OS(D)}$ | Differential short-circuit output current, $ I_{OY} - I_{OZ} $ | \overline{EN} at 0 V, $V_{OY} = V_{OZ}$ | -12 | | 12 | |

(1) Typical values are at room temperature and with a V_{CC} of 3.3 V.

(2) Single-ended input operation is limited to $V_{CC} \geq 3.0$ V.

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating conditions (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|--|--|---|---------------|--------------------|---------------|---------|
| SN65LVP16/17 Y AND Z OUTPUT CHARACTERISTICS | | | | | | |
| V_{OYH} or V_{OZH} | High-level output voltage | 3.3 V; 50 Ω from Y and Z to $V_{CC}-2$ V | $V_{CC}-1.05$ | | $V_{CC}-0.82$ | V |
| V_{OYL} or V_{OZL} | Low-level output voltage | | $V_{CC}-1.83$ | | $V_{CC}-1.57$ | |
| V_{OYL} or V_{OZL} | Low-level output voltage | | $V_{CC}-1.88$ | | $V_{CC}-1.57$ | |
| $ V_{OD} $ | Differential output voltage magnitude, $ V_{OH}-V_{OL} $ | | 0.6 | 0.8 | 1 | |
| I_{OYZ} or I_{OZZ} | High-impedance output current | \overline{EN} at V_{CC} , $V_O = 0$ V or V_{CC} | -1 | | 1 | μ A |
| \overline{Q} OUTPUT CHARACTERISTICS (see Figure 1) | | | | | | |
| V_{OH} | High-level output voltage | No load | | $V_{CC}-0.94$ | | V |
| V_{OL} | Low-level output voltage | GC Tied to GND, No load | | $V_{CC}-1.22$ | | V |
| | | GC Open, No load | | $V_{CC}-1.52$ | | |
| | | GC Tied to V_{CC} , No load | | $V_{CC}-1.82$ | | |
| $V_{O(pp)}$ | Peak-to-peak output voltage | GC Tied to GND | | 300 | | mV |
| | | GC Open | | 575 | | |
| | | GC Tied to V_{CC} | | 860 | | |

SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|----------------|---|--|--------------|--------------------|-----|------|
| t_{PD} | Propagation delay time, t_{PLH} or t_{PHL} | A to \overline{Q} | | 340 | 460 | ps |
| | | D to Y or Z | See Figure 4 | 460 | 630 | |
| $t_{SK(P)}$ | Pulse skew, $ t_{PLH}-t_{PHL} $ | | | 20 | | |
| $t_{SK(PP)}$ | Part-to-part skew ⁽²⁾ | $V_{CC} = 3.3$ V | | | 80 | ps |
| | | $V_{CC} = 2.5$ V | | | 130 | |
| t_r | 20%-to-80% differential signal rise time | See Figure 4 | | 85 | 140 | ps |
| t_f | 20%-to-80% differential signal fall time | See Figure 4 | | 85 | 140 | ps |
| $t_{jit(per)}$ | RMS period jitter ⁽³⁾ | 2-GHz 50%-duty-cycle square-wave input, See Figure 5 | | 2 | 3 | ps |
| $t_{jit(cc)}$ | Peak cycle-to-cycle jitter ⁽⁴⁾ | | | 15 | 23 | |
| $t_{jit(ph)}$ | Intrinsic phase jitter | 2 GHz | | 0.11 | | ps |
| t_{PHZ} | Propagation delay time, high-level-to-high-impedance output | See Figure 6 | | | 30 | ns |
| t_{PLZ} | Propagation delay time, low-level-to-high-impedance output | | | | 30 | |
| t_{PZH} | Propagation delay time, high-impedance-to-high-level output | | | | 30 | |
| t_{PZL} | Propagation delay time, high-impedance-to-low-level output | | | | 30 | |

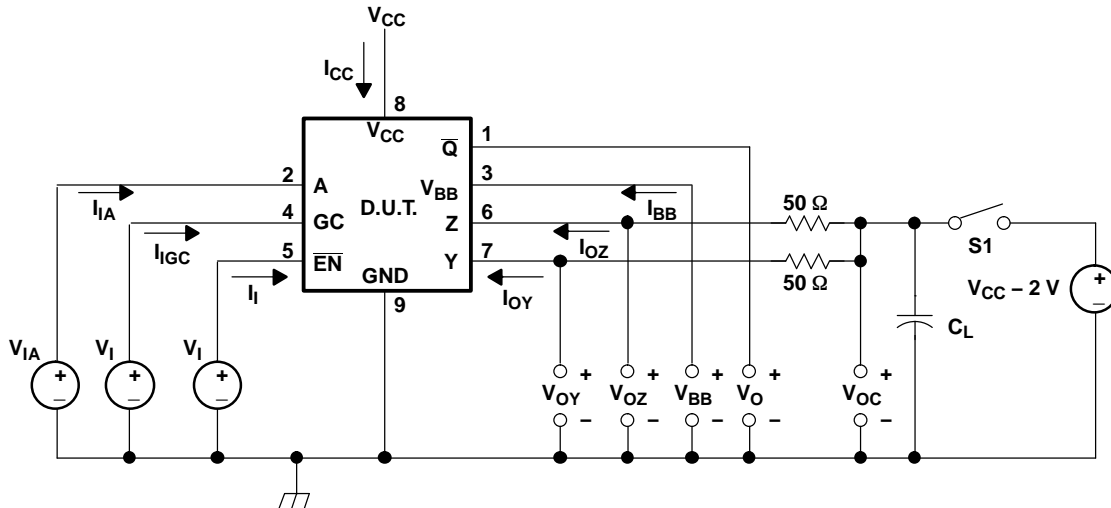
(1) Typical values are at room temperature and with a V_{CC} of 3.3 V.

(2) Part-to-part skew is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

(3) Period jitter is the deviation in cycle time of a signal with respect to the ideal period over a random sample of 100,000 cycles.

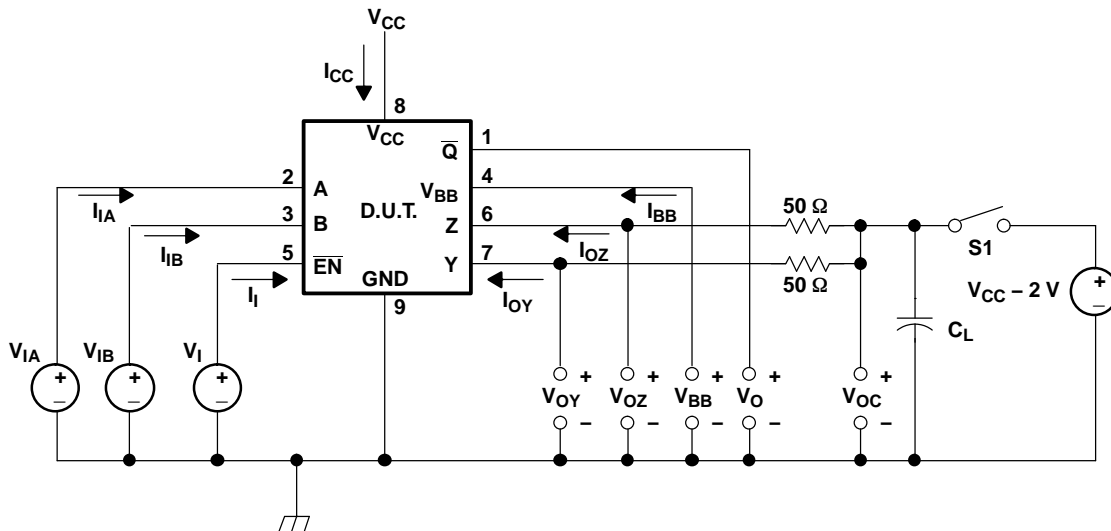
(4) Cycle-to-cycle jitter is the variation in cycle time of a signal between adjacent cycles, over a random sample of 1,000 adjacent cycle pairs.

PARAMETER MEASUREMENT INFORMATION



- (1) C_L is the instrumentation and test fixture capacitance.
- (2) S1 is open for the SN65LVDS16 and closed for the SN65LVP16.

Figure 1. Output Voltage Test Circuit and Voltage and Current Definitions for LVDS/LVP16



- (1) C_L is the instrumentation and test fixture capacitance.
- (2) S1 is open for the SN65LVDS17 and closed for the SN65LVP17.

Figure 2. Output Voltage Test Circuit and Voltage and Current Definitions for LVDS/LVP17

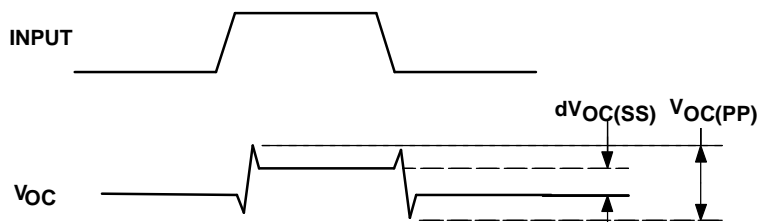


Figure 3. V_{OC} Definitions

PARAMETER MEASUREMENT INFORMATION (continued)

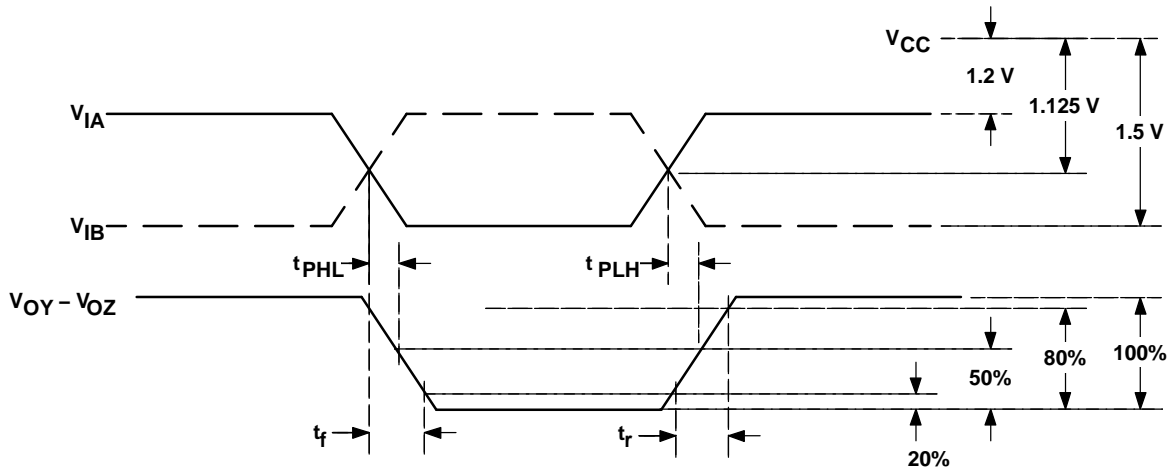


Figure 4. Propagation Delay and Transition Time Test Waveforms

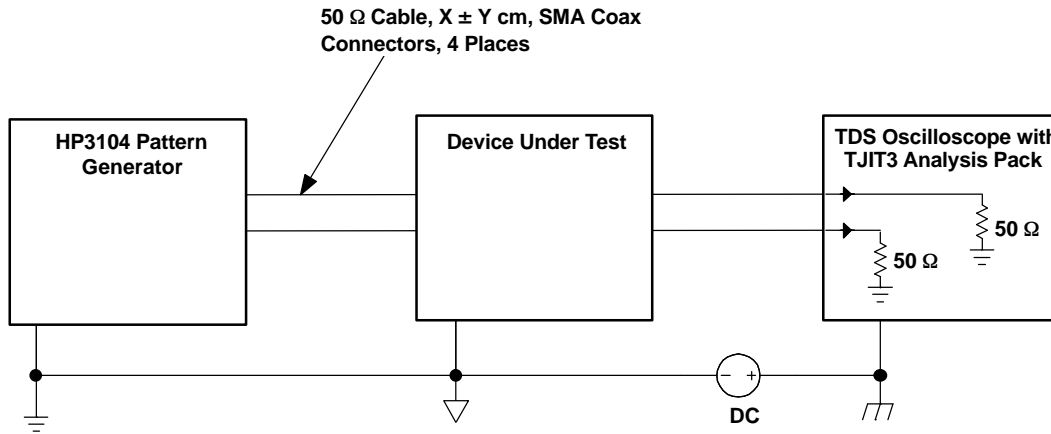


Figure 5. Jitter Measurement Setup

PARAMETER MEASUREMENT INFORMATION (continued)

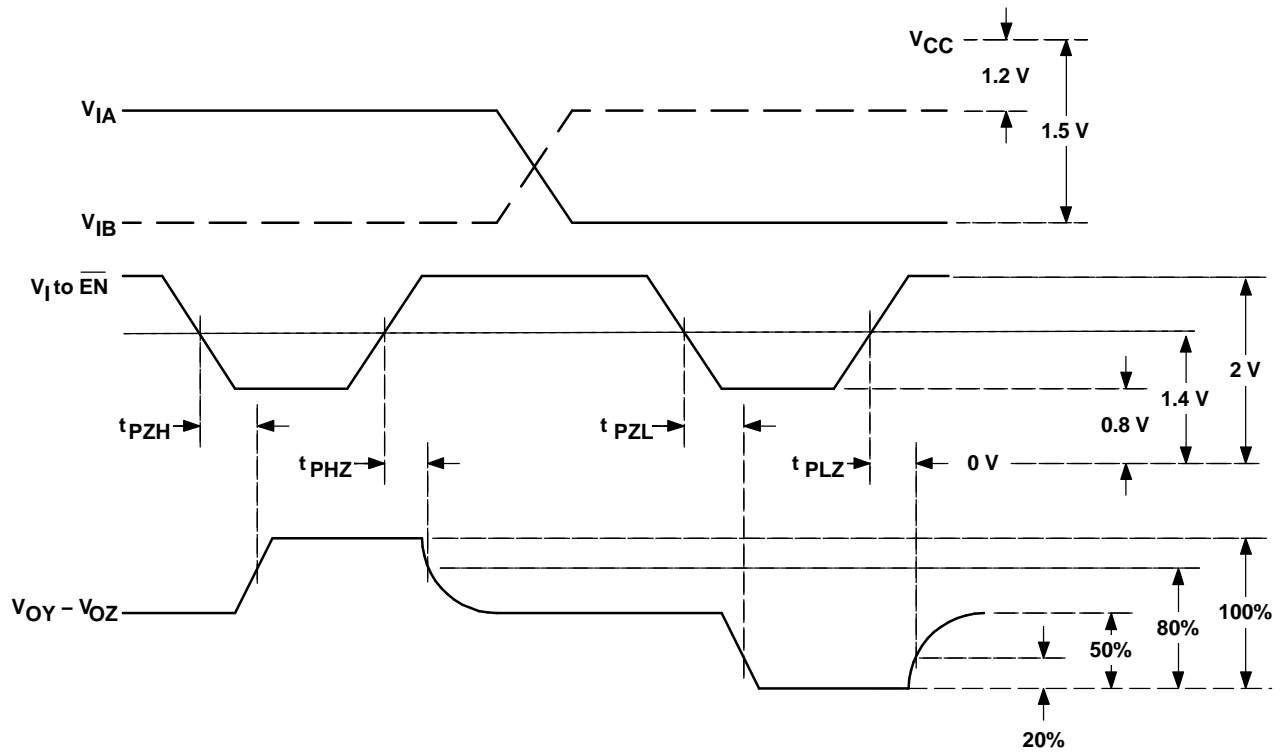


Figure 6. Enable and Disable Time Test Waveforms

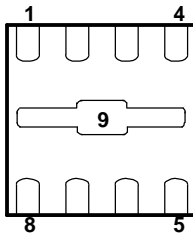
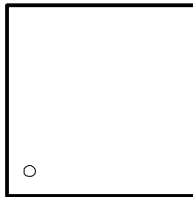
DEVICE INFORMATION

FUNCTION TABLE

| SN65LVDS16, SN65LVP16 ⁽¹⁾ | | | | | SN65LVDS17, SN65LVP17 ⁽¹⁾ | | | | | |
|--------------------------------------|------------------------|-----------------------|---|---|--------------------------------------|------|------------------------|-----------------------|---|---|
| A | $\overline{\text{EN}}$ | $\overline{\text{Q}}$ | Y | Z | A | B | $\overline{\text{EN}}$ | $\overline{\text{Q}}$ | Y | Z |
| H | L | L | H | L | H | H | L | ? | ? | ? |
| L | L | H | L | H | L | H | L | H | L | H |
| X | H | ? | Z | Z | H | L | L | L | H | L |
| Open | L | ? | ? | ? | L | L | L | ? | ? | ? |
| X | Open | ? | ? | ? | X | X | H | ? | Z | Z |
| | | | | | Open | Open | L | ? | ? | ? |
| | | | | | X | X | Open | ? | ? | ? |

(1) H = high, L = low, Z = high impedance, ? = indeterminate

**DRF PACKAGE
TOP VIEW**



BOTTOM VIEW

Package Pin Assignments - Numerical Listing

| SN65LVDS16, SN65LVP16 | | SN65LVDS17, SN65LVP17 | |
|-----------------------|------------------------|-----------------------|------------------------|
| PIN | SIGNAL | PIN | SIGNAL |
| 1 | $\overline{\text{Q}}$ | 1 | $\overline{\text{Q}}$ |
| 2 | A | 2 | A |
| 3 | V_{BB} | 3 | B |
| 4 | GC | 4 | V_{BB} |
| 5 | $\overline{\text{EN}}$ | 5 | $\overline{\text{EN}}$ |
| 6 | Z | 6 | Z |
| 7 | Y | 7 | Y |
| 8 | V_{CC} | 8 | V_{CC} |
| 9 | GND | 9 | GND |

TYPICAL CHARACTERISTICS

**SUPPLY CURRENT
VS
FREQUENCY**

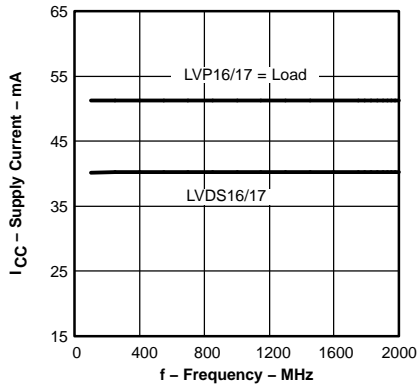


Figure 7.

**SUPPLY CURRENT
VS
FREE-AIR TEMPERATURE**

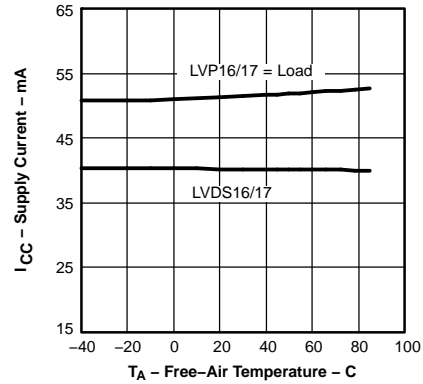


Figure 8.

**LVDS16/17 RISE/FALL TIME
VS
FREE-AIR TEMPERATURE**

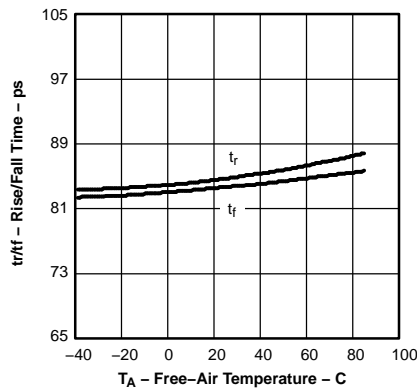


Figure 9.

**LVP16/17 RISE/FALL TIME
VS
FREE-AIR TEMPERATURE**

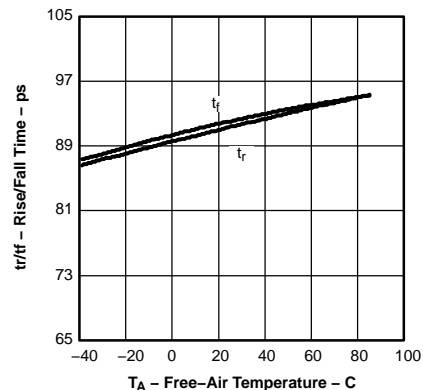


Figure 10.

**LVDS16/17
PROPAGATION DELAY TIME
VS
FREE-AIR TEMPERATURE**

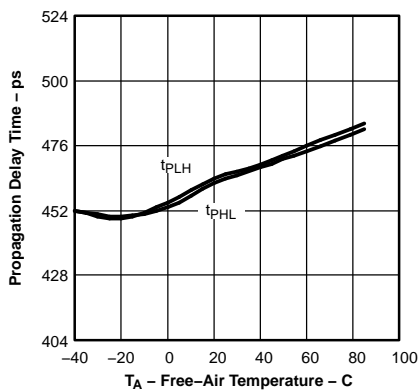


Figure 11.

**PERIOD JITTER
VS
FREQUENCY**

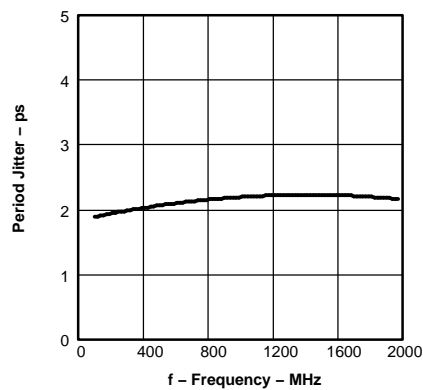


Figure 12.

**CYCLE-TO-CYCLE JITTER
VS
FREQUENCY**

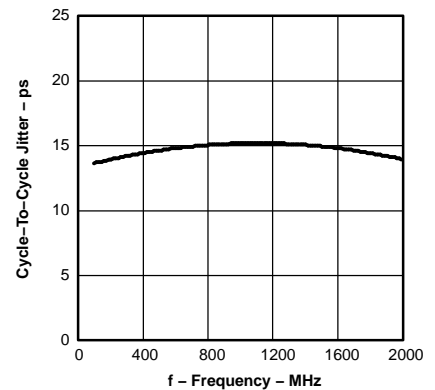
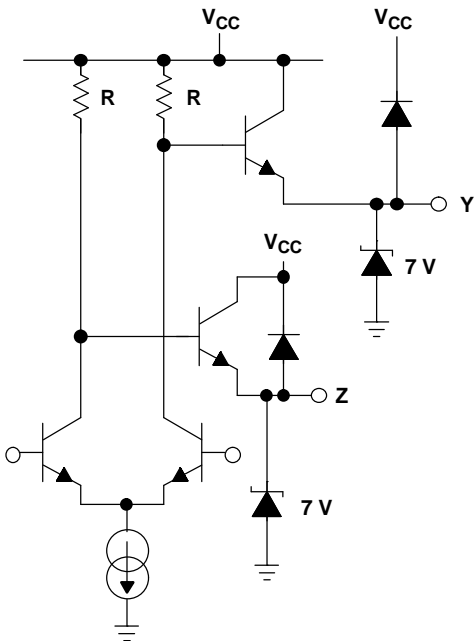


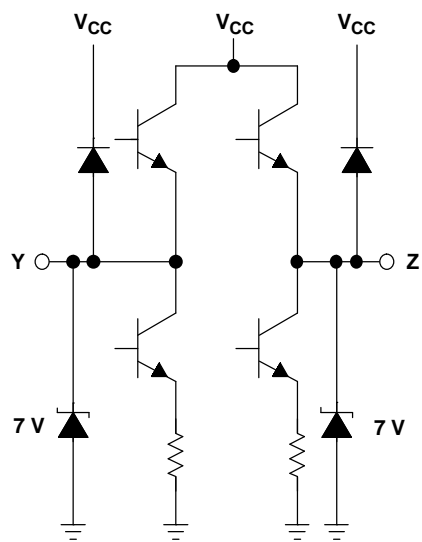
Figure 13.

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS

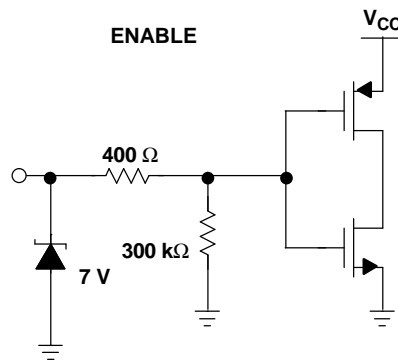
OUTPUT LVP16/17



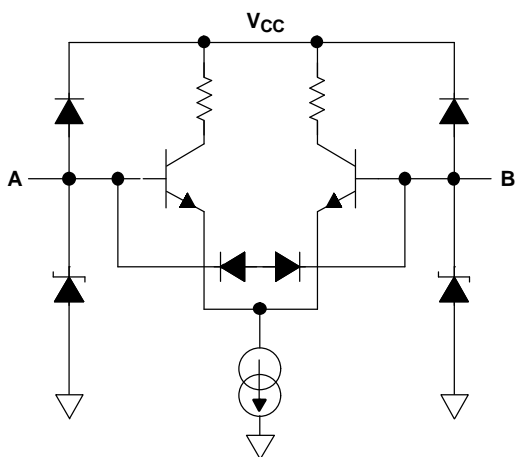
OUTPUT LVDS16/17



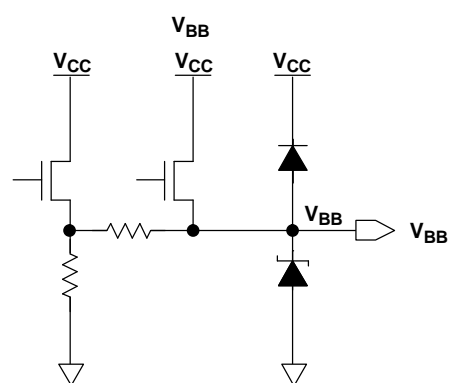
ENABLE



INPUT



OUTPUT



PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN65LVDS16DRFT | ACTIVE | WSON | DRF | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | EL | Samples |
| SN65LVDS17DRFR | ACTIVE | WSON | DRF | 8 | 3000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | EN | Samples |
| SN65LVDS17DRFT | ACTIVE | WSON | DRF | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | EN | Samples |
| SN65LVDS17DRFTG4 | ACTIVE | WSON | DRF | 8 | 250 | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN65LVP16DRFT | ACTIVE | WSON | DRF | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | EK | Samples |
| SN65LVP17DRFT | ACTIVE | WSON | DRF | 8 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | EM | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN65LVDS16DRFT | WSON | DRF | 8 | 250 | 330.0 | 8.8 | 2.3 | 2.3 | 1.0 | 4.0 | 8.0 | Q2 |
| SN65LVDS17DRFR | WSON | DRF | 8 | 3000 | 330.0 | 8.8 | 2.3 | 2.3 | 1.0 | 4.0 | 8.0 | Q2 |
| SN65LVDS17DRFT | WSON | DRF | 8 | 250 | 330.0 | 8.8 | 2.3 | 2.3 | 1.0 | 4.0 | 8.0 | Q2 |
| SN65LVP16DRFT | WSON | DRF | 8 | 250 | 330.0 | 8.8 | 2.3 | 2.3 | 1.0 | 4.0 | 8.0 | Q2 |
| SN65LVP17DRFT | WSON | DRF | 8 | 250 | 330.0 | 8.8 | 2.3 | 2.3 | 1.0 | 4.0 | 8.0 | Q2 |

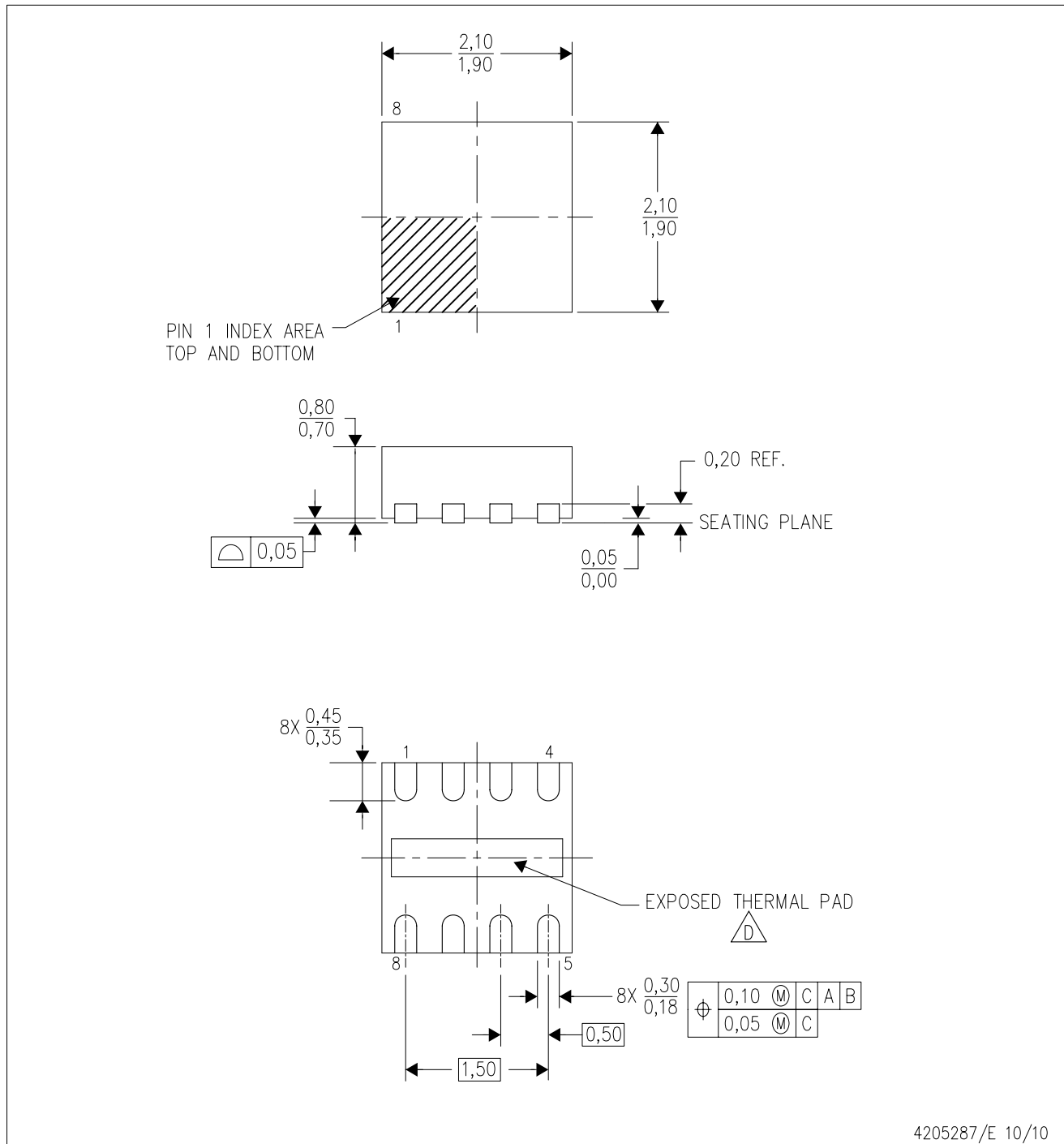
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN65LVDS16DRFT | WSON | DRF | 8 | 250 | 337.0 | 343.0 | 29.0 |
| SN65LVDS17DRFR | WSON | DRF | 8 | 3000 | 337.0 | 343.0 | 29.0 |
| SN65LVDS17DRFT | WSON | DRF | 8 | 250 | 337.0 | 343.0 | 29.0 |
| SN65LVP16DRFT | WSON | DRF | 8 | 250 | 337.0 | 343.0 | 29.0 |
| SN65LVP17DRFT | WSON | DRF | 8 | 250 | 337.0 | 343.0 | 29.0 |

DRF (S-PWSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-Leads (QFN) package configuration.
 -  D. The Package thermal pad must be soldered to the board for thermal and mechanical performance. See product data sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MO-229.

THERMAL PAD MECHANICAL DATA

DRF (S-PWSON-N8)

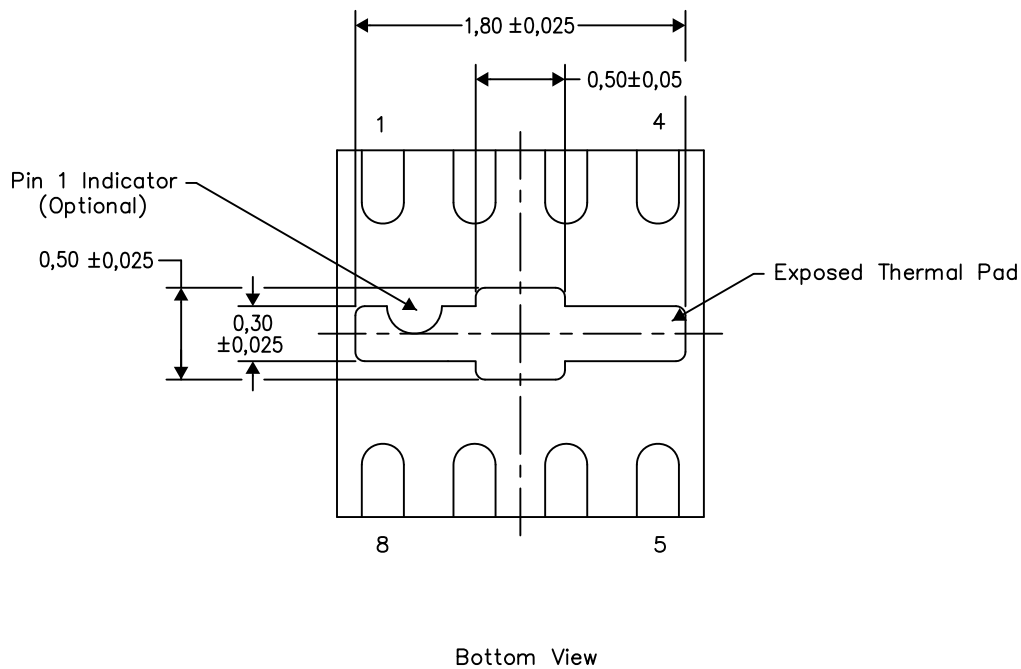
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SOIC PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



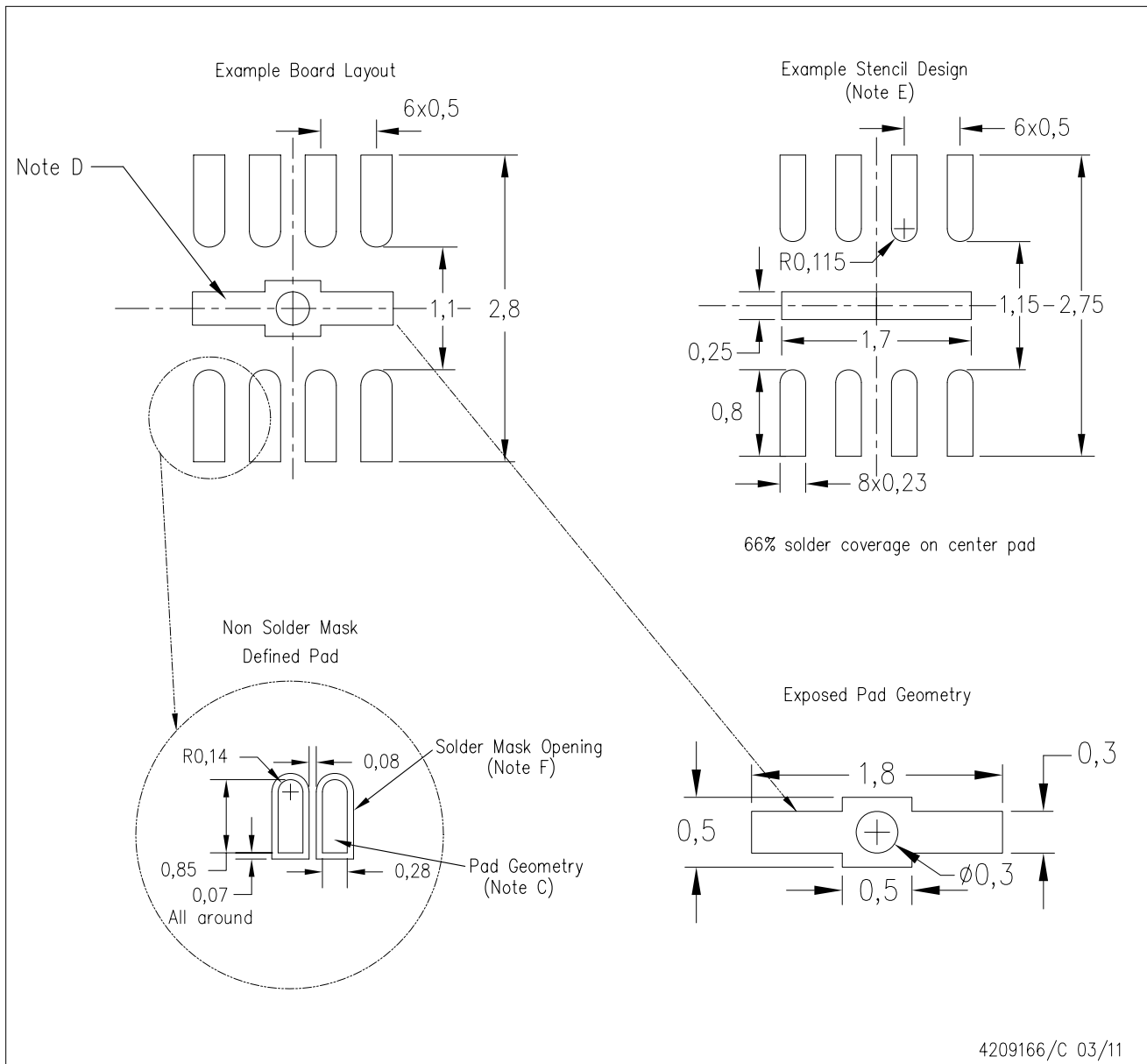
Exposed Thermal Pad Dimensions

4206840/H 12/14

NOTE: A. All linear dimensions are in millimeters

DRF (S-PWSON-N8)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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